



# TECHNICAL BULLETIN

# EPOXIOHM EO-20E ELECTRICALLY CONDUCTIVE EPOXY ADHESIVE

**EO-20E** is a two component, silver-filled epoxy system designed specifically for chip bonding in microelectronic and optoelectronic applications. It is used for thermal management applications due to its high thermal conductivity. It is used for opto-electronic packaging material - LED, LCDs, and fiber optic components.

**EO-20E** is suggested for plastic IC packaging, high power devices and high current flow, High power LEDs. It is also recommended for use in high speed epoxy chip bonding. It is easy to apply by dispensing, screen printing, diestamping, or by hand.

#### **TYPICAL HANDLING PROPERTIES:**

Adhesive	PART A
Hardener	PART B
Mix ratio by weight (Adhesive: Hardener)	1:1
Mix Viscosity @ 25°C, cps	2000-4000
(Cone & Plate viscometer, spindle-51, 50 rpm)	
Work Life (25 grams), hour	>48
Shelf life:	

Two Parts Kit @ 25°C 1 year Frozen @ -40°C 1 year

## **Minimum Bond Line Cure Schedule:**

<1 minute @ 175°C 5-6 minutes @ 150°C 15-20 minutes @ 120°C 120-150 minutes @ 100°C 180-200 minutes @ 80°C

#### **TYPICAL CURED PROPERTIES:**

(Cure 1 hr. @150°C)

Color	Silver	
Specific Gravity	2.6-2.7	
Hardness, Shore D	75	
Lap Shear Strength to Aluminum,	osi 1600	
Volume Resistivity, ohm-cm	< 0.0004	
Glass Transition Temperature (Tg)	, °C 100	
Thermal Conductivity, W/mK	2.5	
Service Temperature (Tg), °C		
Continuous	-55 to 200	
Intermittent	-55 to 300	
Coefficient of Thermal Expansion, 10-6/°C		
Below Tg	30	
Above Tg	>150	
Particle Size	<45 micron	
Ionic Impurities*:		
Chloride (Cl <sup>-</sup> )	< 100 ppm	
Sodium (Na <sup>+</sup> )	< 20 ppm	
Potassium (K <sup>+</sup> )	< 20 ppm	

#### **INSTRUCTIONS FOR USE:**

- 1. Mix each component thoroughly before use.
- Weigh each 10 grams of PART A to 10 grams of PART-B
- 3. Mix until uniform. Scrape the sides and bottom of container repeatedly during mixing.
- 4. Apply to clean bonding surfaces and cure as recommended to achieve the desired properties.
- 5. Typical cured properties were determined using recommended cure schedule.
- Some difference in properties may occur with the alternate or other cure schedules.

Thaw premixed & frozen adhesive at room temperature for 5-10 minutes. Dispense adhesive and cure at recommended schedules.

#### **AVAILABILITY:**

**2 parts Kit** - Packaged in 4 OZ, 8 OZ and 1 lb. container. **Premixed and frozen** - Packaged in 3cc, 5cc and 10cc disposable syringes.

#### **FOR INDUSTRIAL USE ONLY:**

Practices of good housekeeping, safety and cleanliness should be followed before, during and after use.

### **WARNING!**

Adequate ventilation of work-place and ovens is essential. These materials may cause injury to the skin following prolonged or repeated contact and dermatitis in susceptible individuals. In case of skin contact, wash thoroughly with soap and water. For eyes, flush immediately with plenty of water for at least 10 minutes and seek medical attention. Refer to Safety Data Sheet (SDS) for additional health and safety information.